

ABSTRACT OF THE DISCLOSURE

**TITLE OF INVENTION: ABRASIVE PARTICLE, METHOD FOR PRODUCING
THE SAME, AND USE OF THE SAME**

Disclosed is an abrasive particle having an average particle size of not more than 2 μm and comprising 100 parts by weight of aluminum oxide and/or silicon oxide and 5 to 25 parts by weight of cerium in the form of cerium oxide. A method for producing the same, and a use of the abrasive particle for planarizing an insulating film on a semiconductor substrate.

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